



Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	55
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	7K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212aasnf-p-v2

Table 1.2 Specifications for R8C/2A Group (2)

Item	Function	Specification
Serial Interface	UART0, UART1, UART2	Clock synchronous serial I/O/UART × 3
Clock Synchronous Serial I/O with Chip Select (SSU)		1 (shared with I ² C-bus)
I ² C bus ⁽¹⁾		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function
D/A Converter		8-bit resolution × 2 circuits
Flash Memory		• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 100 times • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 3.0 to 5.5 V) f(XIN) = 10 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 2.2 to 5.5 V)
Current consumption		12 mA (VCC = 5.0 V, f(XIN) = 20 MHz) 5.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) 2.1 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) 0.65 μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		-20 to 85°C (N version) -40 to 85°C (D version) ⁽²⁾ -20 to 105°C (Y version) ⁽³⁾
Package		64-pin LQFP • Package code: PLQP0064KB-A (previous code: 64P6Q-A) • Package code: PLQP0064GA-A (previous code: 64P6U-A) 64-pin FLGA • Package code: PTLG0064JA-A (previous code: 64F0G)

NOTES:

1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
2. Specify the D version if D version functions are to be used.
3. Please contact Renesas Technology sales offices for the Y version.

Table 1.6 Product List for R8C/2B Group

Current of Nov. 2007

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks	
	Program ROM	Data flash				
R5F212B7SNFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064KB-A	N version	
R5F212B7SNFA	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064GA-A		
R5F212B7SNLG	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PTLG0064JA-A		
R5F212B8SNFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064KB-A		
R5F212B8SNFA	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064GA-A		
R5F212B8SNLG	64 Kbytes	1 Kbyte × 2	3 Kbytes	PTLG0064JA-A		
R5F212BASNFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064KB-A		
R5F212BASNFA	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064GA-A		
R5F212BASNLG	96 Kbytes	1 Kbyte × 2	7 Kbytes	PTLG0064JA-A		
R5F212BCSNFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064KB-A		
R5F212BCSNFA	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064GA-A		
R5F212BCSNLG	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PTLG0064JA-A		
R5F212B7SDFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064KB-A	D version	
R5F212B7SDFA	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064GA-A		
R5F212B8SDFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064KB-A		
R5F212B8SDFA	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064GA-A		
R5F212BASDFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064KB-A		
R5F212BASDFA	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064GA-A		
R5F212BCSDFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064KB-A		
R5F212BCSDFA	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064GA-A		
R5F212B7SNXXXFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064KB-A	N version	Factory programming product ⁽¹⁾
R5F212B7SNXXXFA	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064GA-A		
R5F212B7SNXXXLG	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PTLG0064JA-A		
R5F212B8SNXXXFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064KB-A		
R5F212B8SNXXXFA	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064GA-A		
R5F212B8SNXXXLG	64 Kbytes	1 Kbyte × 2	3 Kbytes	PTLG0064JA-A		
R5F212BASNXXXFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064KB-A		
R5F212BASNXXXFA	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064GA-A		
R5F212BASNXXXLG	96 Kbytes	1 Kbyte × 2	7 Kbytes	PTLG0064JA-A		
R5F212BCSNXXXFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064KB-A		
R5F212BCSNXXXFA	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064GA-A		
R5F212BCSNXXXLG	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PTLG0064JA-A		
R5F212B7SDXXXFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064KB-A	D version	
R5F212B7SDXXXFA	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064GA-A		
R5F212B8SDXXXFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064KB-A		
R5F212B8SDXXXFA	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064GA-A		
R5F212BASDXXXFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064KB-A		
R5F212BASDXXXFA	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064GA-A		
R5F212BCSDXXXFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064KB-A		
R5F212BCSDXXXFA	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064GA-A		

NOTE:

1. The user ROM is programmed before shipment.

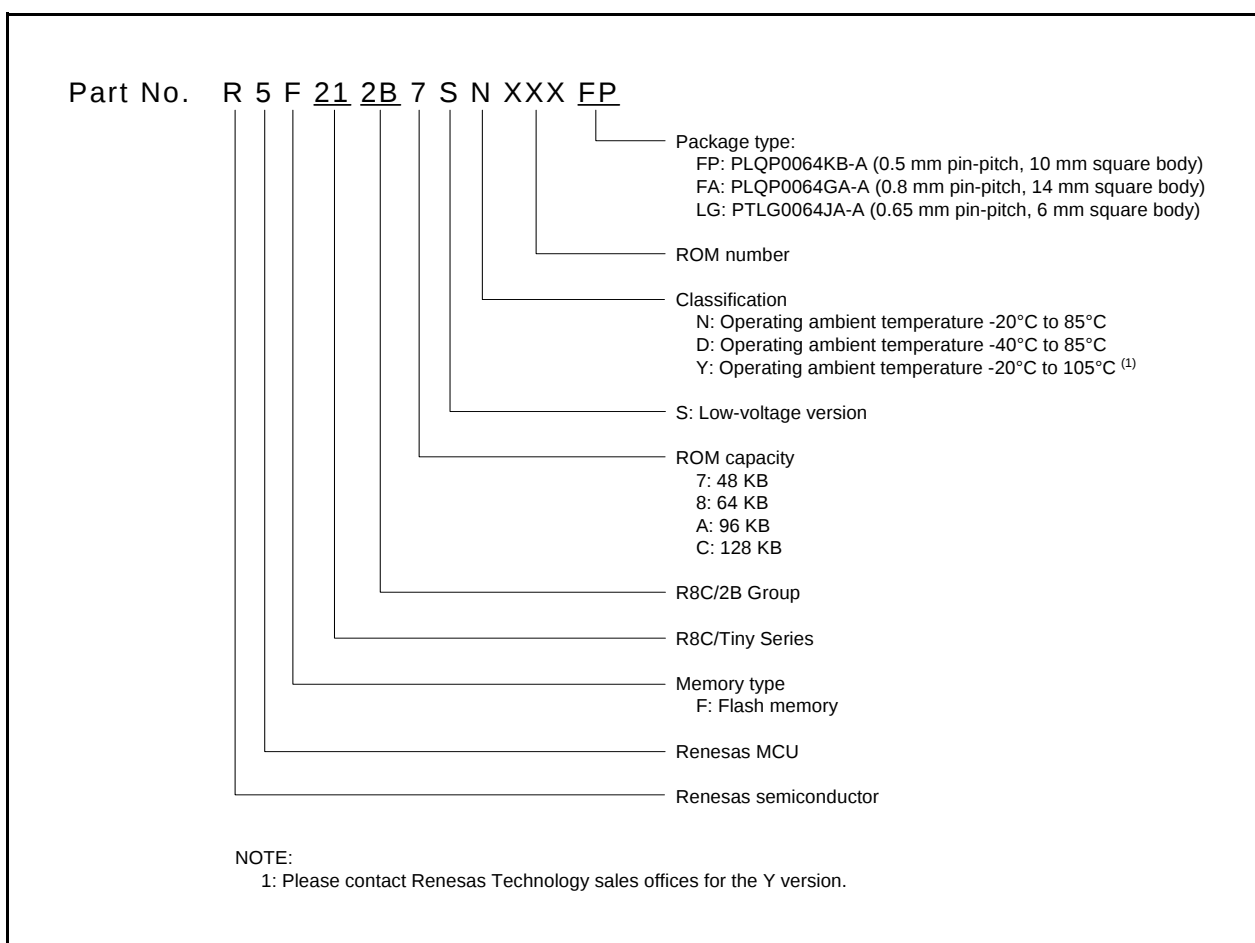


Figure 1.2 Part Number, Memory Size, and Package of R8C/2B Group

1.3 Block Diagram

Figure 1.3 shows a Block Diagram.

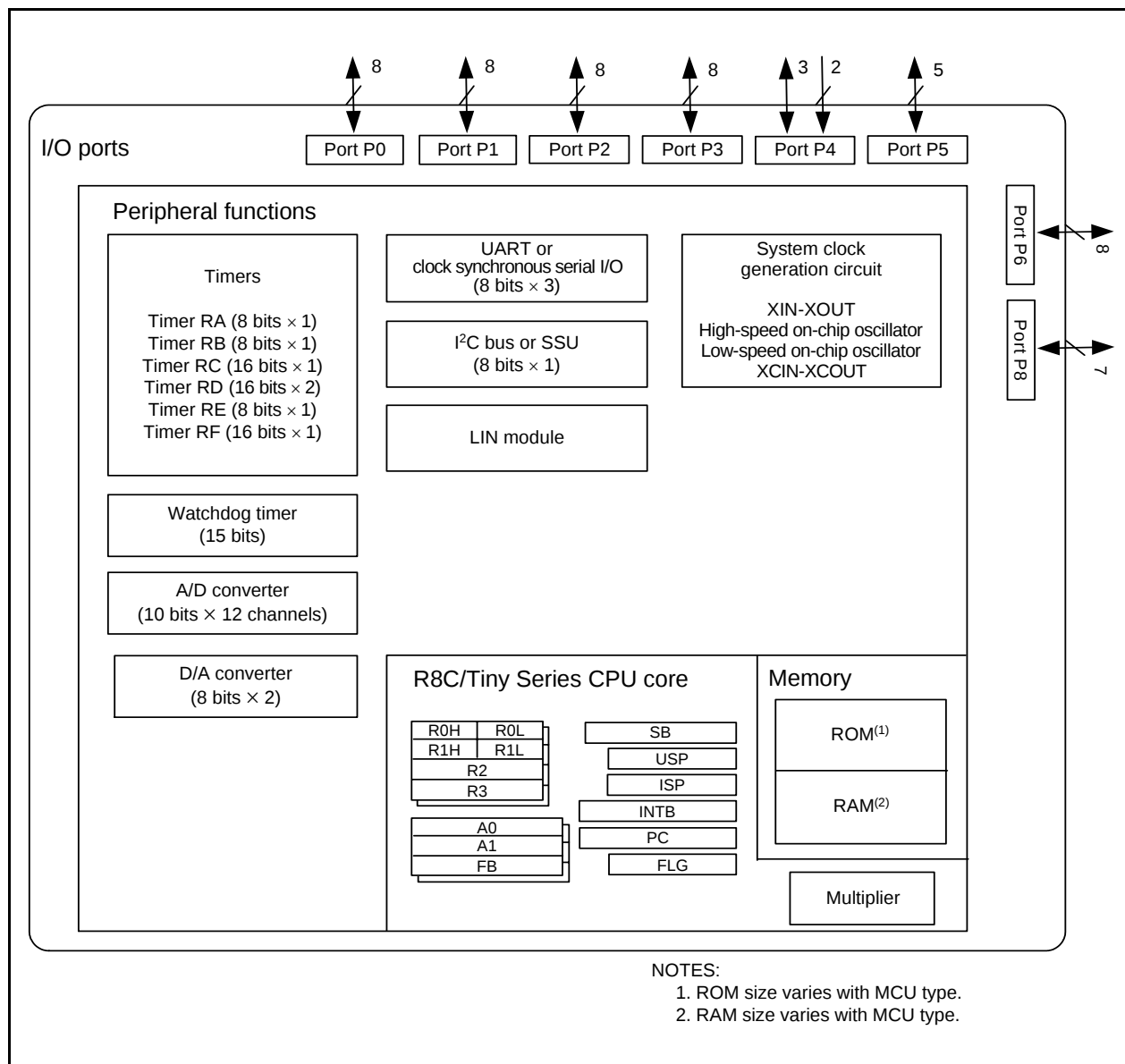


Figure 1.3 Block Diagram

1.4 Pin Assignment

Figure 1.4 shows 64-pin LQFP Package Pin Assignment (Top View). Figure 1.5 shows 64-pin FLGA Package Pin Assignment (Top Perspective View). Tables 1.7 and 1.8 outlines the Pin Name Information by Pin Number.

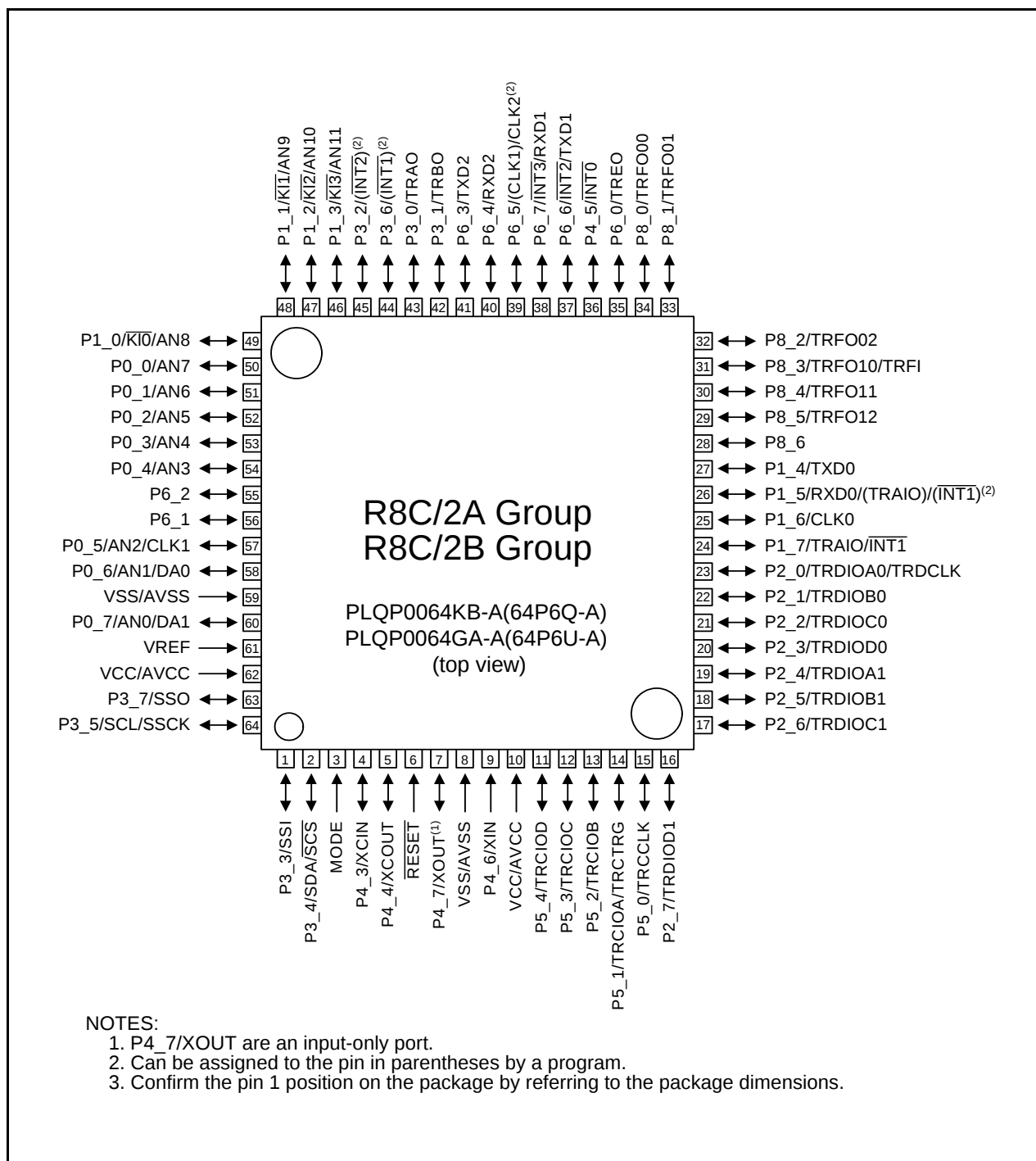


Figure 1.4 64-pin LQFP Package Pin Assignment (Top View)

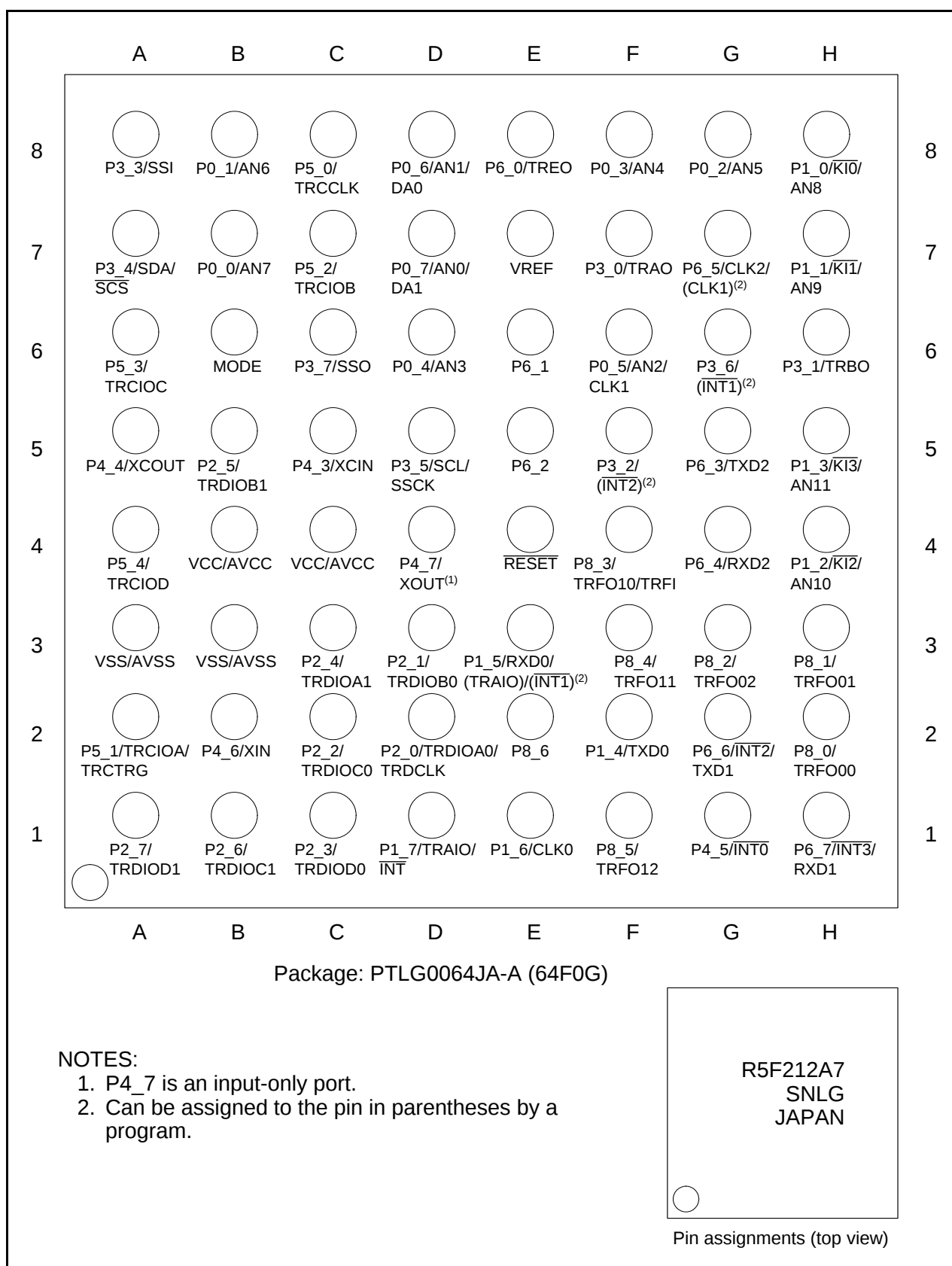


Figure 1.5 64-pin FLGA Package Pin Assignment (Top Perspective View)

Table 1.10 Pin Functions (2)

Item	Pin Name	I/O Type	Description
A/D converter	AN0 to AN11	I	Analog input pins to A/D converter
D/A converter	DA0 to DA1	O	D/A converter output pins
I/O port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_3 to P4_5, P5_0 to P5_4, P6_0 to P6_7, P8_0 to P8_6	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. P2_0 to P2_7 also function as LED drive ports.
Input port	P4_6, P4_7	I	Input-only ports

I: Input O: Output I/O: Input and output

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.

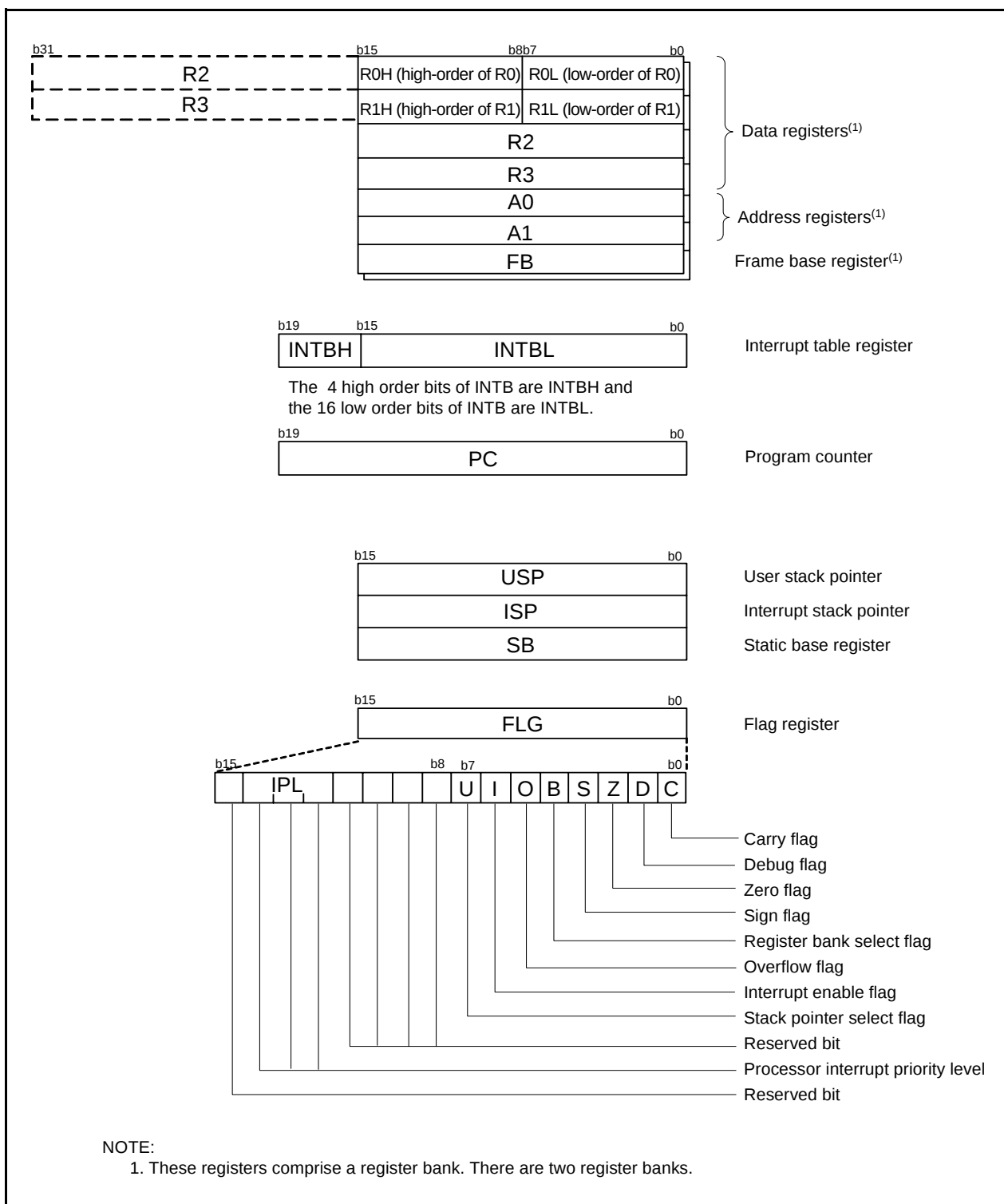


Figure 2.1 CPU Registers

Table 4.8 SFR Information (8)⁽¹⁾

Address	Register	Symbol	After reset
01C0h			
01C1h			
01C2h			
01C3h			
01C4h			
01C5h			
01C6h			
01C7h			
01C8h			
01C9h			
01CAh			
01CBh			
01CCh			
01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h			
01E1h			
01E2h			
01E3h			
01E4h			
01E5h			
01E6h			
01E7h			
01E8h			
01E9h			
01EAh			
01EBh			
01ECh			
01EDh			
01EEh			
01EFh			
01F0h			
01F1h			
01F2h			
01F3h			
01F4h			
01F5h			
01F6h			
01F7h			
01F8h			
01F9h			
01FAh			
01FBh			
01FCh			
01FDh			
01FEh			
01FFh			

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.9 SFR Information (9)⁽¹⁾

Address	Register	Symbol	After reset
0200h			
0201h			
0202h			
0203h			
0204h			
0205h			
0206h			
0207h			
0208h			
0209h			
020Ah			
020Bh			
020Ch			
020Dh			
020Eh			
020Fh			
0210h			
0211h			
0212h			
0213h			
0214h			
0215h			
0216h			
0217h			
0218h			
0219h			
021Ah			
021Bh			
021Ch			
021Dh			
021Eh			
021Fh			
0220h			
0221h			
0222h			
0223h			
0224h			
0225h			
0226h			
0227h			
0228h			
0229h			
022Ah			
022Bh			
022Ch			
022Dh			
022Eh			
022Fh			
0230h			
0231h			
0232h			
0233h			
0234h			
0235h			
0236h			
0237h			
0238h			
0239h			
023Ah			
023Bh			
023Ch			
023Dh			
023Eh			
023Fh			

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.10 SFR Information (10)(1)

Address	Register	Symbol	After reset
0240h			
0241h			
0242h			
0243h			
0244h			
0245h			
0246h			
0247h			
0248h			
0249h			
024Ah			
024Bh			
024Ch			
024Dh			
024Eh			
024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh			
025Fh			
0260h			
0261h			
0262h			
0263h			
0264h			
0265h			
0266h			
0267h			
0268h			
0269h			
026Ah			
026Bh			
026Ch			
026Dh			
026Eh			
026Fh			
0270h			
0271h			
0272h			
0273h			
0274h			
0275h			
0276h			
0277h			
0278h			
0279h			
027Ah			
027Bh			
027Ch			
027Dh			
027Eh			
027Fh			

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.12 SFR Information (12)(1)

Address	Register	Symbol	After reset
02C0h	A/D Register 0	AD0	XXh
02C1h			XXh
02C2h			
02C3h			
02C4h			
02C5h			
02C6h			
02C7h			
02C8h			
02C9h			
02CAh			
02CBh			
02CCh			
02CDh			
02CEh			
02CFh			
02D0h			
02D1h			
02D2h			
02D3h			
02D4h	A/D Control Register 2	ADCON2	00001000b
02D5h			
02D6h	A/D Control Register 0	ADCON0	00000011b
02D7h	A/D Control Register 1	ADCON1	00h
02D8h			
02D9h			
02DAh			
02DBh			
02DCh			
02DDh			
02DEh			
02DFh			
02E0h			
02E1h			
02E2h			
02E3h			
02E4h	Port P8 Direction Register	PD8	00h
02E5h			
02E6h	Port P8 Register	P8	XXh
02E7h			
02E8h			
02E9h			
02EAh			
02EBh			
02ECh			
02EDh			
02EEh			
02EFh			
02F0h			
02F1h			
02F2h			
02F3h			
02F4h			
02F5h			
02F6h			
02F7h			
02F8h			
02F9h			
02FAh			
02FBh			
02FCh	Pull-Up Control Register 2	PUR2	XXX00000b
02FDh			
02FEh			
02FFh	Timer RF Output Control Register	TRFOUT	00h
FFFFh	Option Function Select Register	OFS	(Note 2)

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. The OFS register cannot be changed by a program. Use a flash programmer to write to it.

Table 5.11 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO40M	High-speed on-chip oscillator frequency temperature • supply voltage dependence	V _{CC} = 2.7 V to 5.5 V -20°C ≤ T _{opr} ≤ 85°C ⁽²⁾	39.2	40	40.8	MHz
		V _{CC} = 2.7 V to 5.5 V -40°C ≤ T _{opr} ≤ 85°C ⁽²⁾	39.0	40	41.0	MHz
		V _{CC} = 2.2 V to 5.5 V -20°C ≤ T _{opr} ≤ 85°C ⁽³⁾	35.2	40	44.8	MHz
		V _{CC} = 2.2 V to 5.5 V -40°C ≤ T _{opr} ≤ 85°C ⁽³⁾	34.0	40	46.0	MHz
	High-speed on-chip oscillator frequency when correction value in FRA7 register is written to FRA1 register	V _{CC} = 5.0 V, T _{opr} = 25°C	–	36.864	–	MHz
		V _{CC} = 2.7 V to 5.5 V -20°C ≤ T _{opr} ≤ 85°C	-3%	–	3%	%
–	Value in FRA1 register after reset		08h	–	F7h	–
–	Oscillation frequency adjustment unit of high- speed on-chip oscillator	Adjust FRA1 register (value after reset) to -1	–	+0.3	–	MHz
–	Oscillation stability time	V _{CC} = 5.0 V, T _{opr} = 25°C	–	10	100	μs
–	Self power consumption at oscillation	V _{CC} = 5.0 V, T _{opr} = 25°C	–	550	–	μA

NOTES:

1. V_{CC} = 2.2 to 5.5 V, T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. These standard values show when the FRA1 register value after reset is assumed.
3. These standard values show when the correction value in the FRA6 register is written to the FRA1 register.

Table 5.12 Low-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		30	125	250	kHz
–	Oscillation stability time	V _{CC} = 5.0 V, T _{opr} = 25°C	–	10	100	μs
–	Self power consumption at oscillation	V _{CC} = 5.0 V, T _{opr} = 25°C	–	15	–	μA

NOTE:

1. V_{CC} = 2.2 to 5.5 V, T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.

Table 5.13 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _d (P-R)	Time for internal power supply stabilization during power-on ⁽²⁾		1	–	2000	μs
t _d (R-S)	STOP exit time ⁽³⁾		–	–	150	μs

NOTES:

1. The measurement condition is V_{CC} = 2.2 to 5.5 V and T_{opr} = 25°C.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.
3. Time until system clock supply starts after the interrupt is acknowledged to exit stop mode.

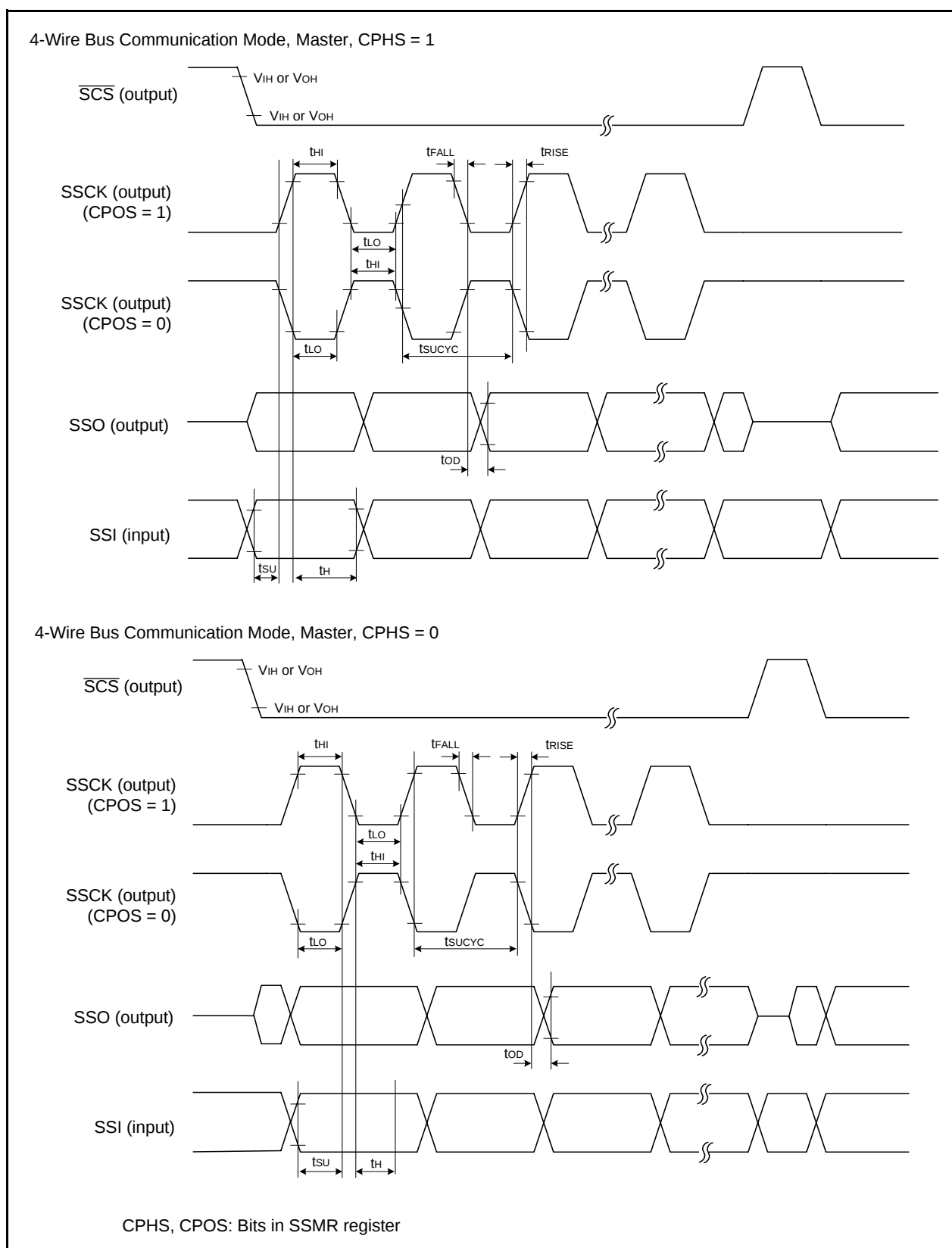


Figure 5.4 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Master)

Table 5.16 Electrical Characteristics (1) [V_{CC} = 5 V]

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except P2_0 to P2_7, XOUT	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
			I _{OH} = -200 μ A	V _{CC} - 0.5	—	V _{CC}	V
		P2_0 to P2_7	Drive capacity HIGH I _{OH} = -20 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
		XOUT	Drive capacity HIGH I _{OH} = -1 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -500 μ A	V _{CC} - 2.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P2_0 to P2_7, XOUT	I _{OL} = 5 mA	—	—	2.0	V
			I _{OL} = 200 μ A	—	—	0.45	V
		P2_0 to P2_7	Drive capacity HIGH I _{OL} = 20 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 5 mA	—	—	2.0	V
		XOUT	Drive capacity HIGH I _{OL} = 1 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 500 μ A	—	—	2.0	V
V _{T+} -V _{T-}	Hysteresis	<u>INT0</u> , <u>INT1</u> , <u>INT2</u> , <u>INT3</u> , <u>KI0</u> , <u>KI1</u> , <u>KI2</u> , <u>KI3</u> , <u>TRAIO</u> , <u>TRFI</u> , <u>RXD0</u> , <u>RXD1</u> , <u>CLK0</u> , <u>CLK1</u> , <u>CLK2</u> , <u>SSI</u> , <u>SCL</u> , <u>SDA</u> , <u>SSO</u>		0.1	0.5	—	V
		<u>RESET</u>		0.1	1.0	—	V
I _{IH}	Input "H" current		V _I = 5 V	—	—	5.0	μ A
I _{IL}	Input "L" current		V _I = 0 V	—	—	-5.0	μ A
R _{PULLUP}	Pull-up resistance		V _I = 0 V	30	50	167	k Ω
R _{FXIN}	Feedback resistance	XIN		—	1.0	—	M Ω
R _{FXCIN}	Feedback resistance	XCIN		—	18	—	M Ω
V _{RAM}	RAM hold voltage		During stop mode	1.8	—	—	V

NOTE:

- V_{CC} = 4.2 to 5.5 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.23 Electrical Characteristics (3) [V_{CC} = 3 V]

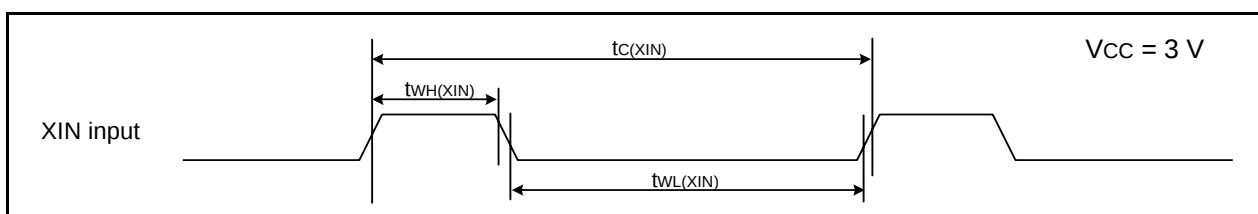
Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except P2_0 to P2_7, XOUT	I _{OH} = -1 mA		V _{CC} - 0.5	—	V _{CC}	V
		P2_0 to P2_7	Drive capacity HIGH	I _{OH} = -5 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity LOW	I _{OH} = -1 mA	V _{CC} - 0.5	—	V _{CC}	V
		XOUT	Drive capacity HIGH	I _{OH} = -0.1 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity LOW	I _{OH} = -50 μA	V _{CC} - 0.5	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P2_0 to P2_7, XOUT	I _{OL} = 1 mA		—	—	0.5	V
		P2_0 to P2_7	Drive capacity HIGH	I _{OL} = 5 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 1 mA	—	—	0.5	V
		XOUT	Drive capacity HIGH	I _{OL} = 0.1 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 50 μA	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, KI0, KI1, KI2, KI3, TRAIO, TRFI, RXD0, RXD1, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.1	0.3	—	V
		RESET			0.1	0.4	—	V
I _{IH}	Input "H" current		V _I = 3 V		—	—	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V		—	—	-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V		66	160	500	kΩ
R _{IXIN}	Feedback resistance	XIN			—	3.0	—	MΩ
R _{IXCIN}	Feedback resistance	XCIN			—	18	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

NOTE:

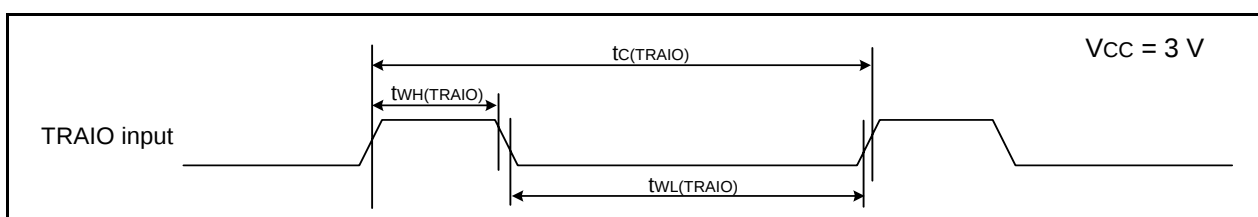
- V_{CC} = 2.7 to 3.3 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 10 MHz, unless otherwise specified.

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^\circ\text{C}$) [$V_{CC} = 3\text{ V}$]****Table 5.25 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	–	ns
$t_{WH(XIN)}$	XIN input “H” width	40	–	ns
$t_{WL(XIN)}$	XIN input “L” width	40	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.13 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.26 TRAIO Input, $\overline{\text{INT1}}$ Input**

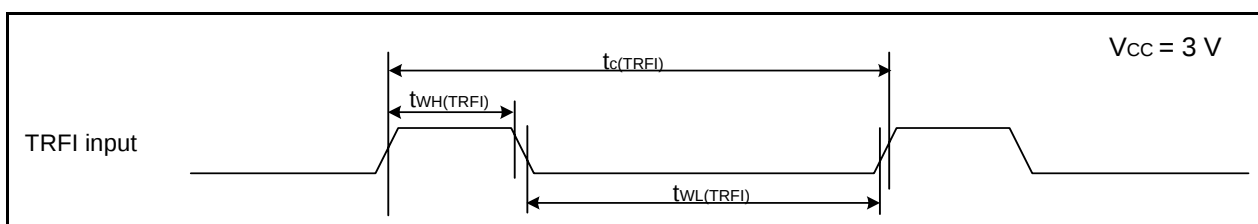
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	120	–	ns

**Figure 5.14 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.27 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	1200 ⁽¹⁾	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	600 ⁽²⁾	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	600 ⁽²⁾	–	ns

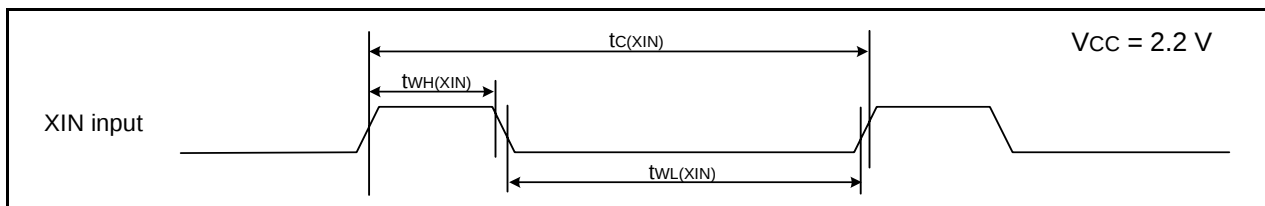
NOTES:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

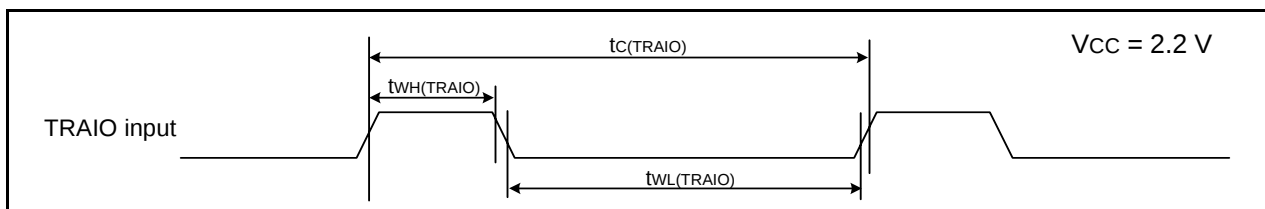
**Figure 5.15 TRFI Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 2.2\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^\circ\text{C}$) [$V_{CC} = 2.2\text{ V}$]****Table 5.32 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	200	–	ns
$t_{WH(XIN)}$	XIN input “H” width	90	–	ns
$t_{WL(XIN)}$	XIN input “L” width	90	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.18 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.33 TRAIO Input, $\overline{\text{INT1}}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	TBD	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	TBD	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	TBD	–	ns

**Figure 5.19 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.34 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	2000 ⁽¹⁾	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	1000 ⁽²⁾	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	1000 ⁽²⁾	–	ns

NOTES:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

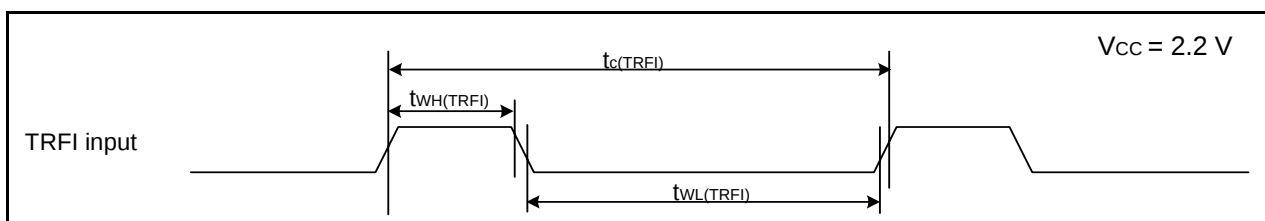
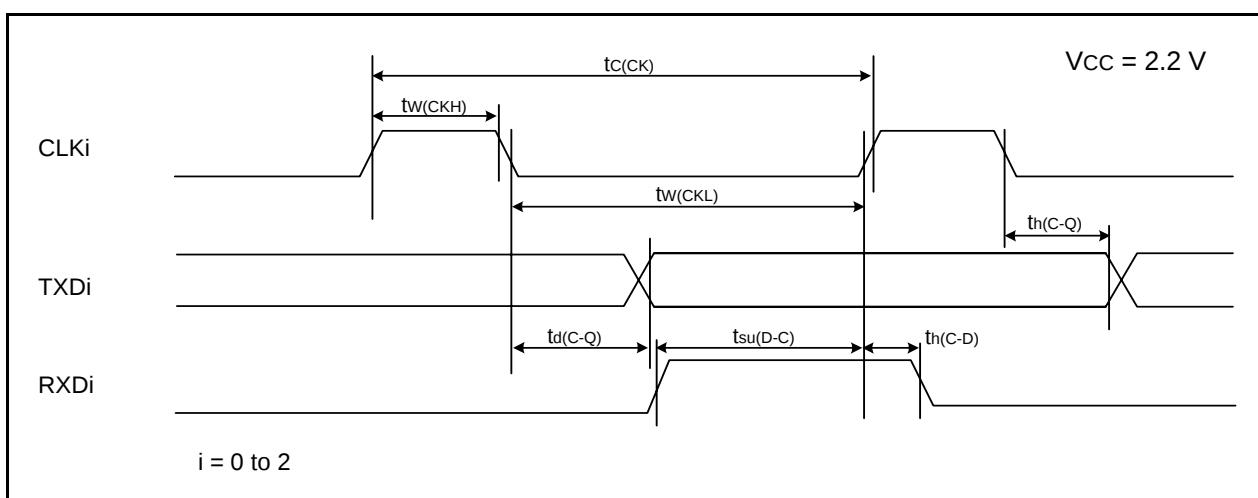
**Figure 5.20 TRFI Input Timing Diagram when $V_{CC} = 2.2\text{ V}$**

Table 5.35 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	ns
$t_{w(CKH)}$	CLKi input "H" width	400	—	ns
$t_{w(CKL)}$	CLKi input "L" width	400	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

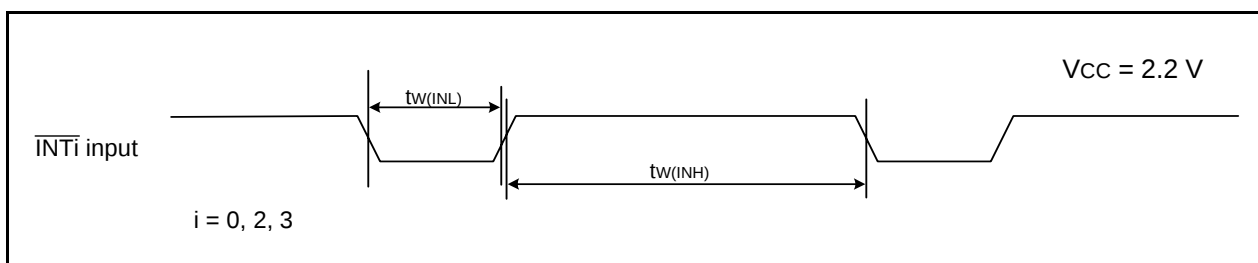
i = 0 to 2

**Figure 5.21 Serial Interface Timing Diagram when Vcc = 2.2 V****Table 5.36 External Interrupt $\overline{INTi}$ (i = 0, 2, 3) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	1000 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	1000 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.

**Figure 5.22 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 2.2 V**

REVISION HISTORY	R8C/2A Group, R8C/2B Group Datasheet
------------------	--------------------------------------

Rev.	Date	Description	
		Page	Summary
0.01	Apr 03, 2006	–	First Edition issued
0.10	Jun 26, 2006	All pages	Pin name revised CMP0_0 → TRFO00, CMP0_1 → TRFO01, CMP0_2 → TRFO02, CMP1_0 → TRFO10, CMP1_1 → TRFO11, CMP1_2 → TRFO12, TRFIN → TRFI
		2, 4	Table 1.1 Specifications for R8C/2A Group (1) and Table 1.3 Specifications for R8C/2B Group (1); I/O Ports: • Input-only: 3 pins → 2 pins revised Interrupts: • Internal: 17 sources → 23 sources revised
		3, 5	Table 1.2 Specifications for R8C/2A Group (2) and Table 1.4 Specifications for R8C/2B Group (2); ROM Correction Function deleted
		8	Figure 1.3 Block Diagram revised
		9	Figure 1.4 Pin Assignment (Top View) revised
		10, 11	Table 1.7 Pin Name Information by Pin Number (1) and Table 1.8 Pin Name Information by Pin Number (2) revised
		12, 13	Table 1.9 Pin Functions (1) and Table 1.10 Pin Functions (2) revised
		19	Table 4.1 SFR Information (1); • 0008h: Module Standby Control Register, MSTCR, 00h added • 001Ch: “00h” → “00h, 10000000b” revised • NOTE6 added
		20	Table 4.2 SFR Information (2); • 005Fh: Capture Interrupt Control Register, CAPIC, XXXXX000b added
		22	Table 4.4 SFR Information (4); • 00DCh: “00DDh” → “00DCh” revised • 00F5h: “XXXX00XXb” → “00h” revised
		23	Table 4.5 SFR Information (5); • 0105h: LIN Special Function Register, LINCR2, 00h added
		30	Table 4.12 SFR Information (12); • 02C2h, 02C3h: A/D Register 1, AD1, XXh deleted • 02C4h, 02C5h: A/D Register 2, AD2, XXh deleted • 02C6h, 02C7h: A/D Register 3, AD3, XXh deleted
		31	Package Dimensions; “Diagrams showing the latest package dimensions... in the “Packages” section of the Renesas Technology website.” added
0.20	Sep 15, 2006	31 to 54	5. Electrical Characteristics added
0.30	Dec 22, 2006	6	Table 1.5 and Figure 1.1 revised
		7	Table 1.6 and Figure 1.2 revised
		17	Figure 3.1 revised
		18	Figure 3.2 revised